Lattice Semiconductor Corporation - LFE2M35E-6FN256C Datasheet

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	4250
Number of Logic Elements/Cells	34000
Total RAM Bits	2151424
Number of I/O	140
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	256-BGA
Supplier Device Package	256-FPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfe2m35e-6fn256c

Table 1-2. LatticeECP2M (Including "S-Series") Family Selection

Device	ECP2M20	ECP2M35	ECP2M50	ECP2M70	ECP2M100
LUTs (K)	19	34	48	67	95
sysMEM Blocks (18kb)	66	114	225	246	288
Embedded Memory (Kbits)	1217	2101	4147	4534	5308
Distributed Memory (Kbits)	41	71	101	145	202
sysDSP Blocks	6	8	22	24	42
18x18 Multipliers	24	32	88	96	168
GPLL+SPLL+DLL	2+6+2	2+6+2	2+6+2	2+6+2	2+6+2
Maximum Available I/O	304	410	410	436	520
Packages and SERDES / I/O Combinations					
256-ball fpBGA (17 x 17 mm)	4 / 140	4 / 140			
484-ball fpBGA (23 x 23 mm)	4 / 304	4 / 303	4 / 270		
672-ball fpBGA (27 x 27 mm)		4 / 410	8 / 372		
900-ball fpBGA (31 x 31 mm)			8 / 410	16 / 416	16 / 416
1152-ball fpBGA (35 x 35 mm)				16 / 436	16 / 520

Introduction

The LatticeECP2/M family of FPGA devices is optimized to deliver high performance features such as advanced DSP blocks, high speed SERDES (LatticeECP2M family only) and high speed source synchronous interfaces in an economical FPGA fabric. This combination was achieved through advances in device architecture and the use of 90nm technology.

The LatticeECP2/M FPGA fabric is optimized with high performance and low cost in mind. The LatticeECP2/M devices include LUT-based logic, distributed and embedded memory, Phase Locked Loops (PLLs), Delay Locked Loops (DLLs), pre-engineered source synchronous I/O support, enhanced sysDSP blocks and advanced configuration support, including encryption ("S" versions only) and dual boot capabilities.

The LatticeECP2M device family features high speed SERDES with PCS. These high jitter tolerance and low transmission jitter SERDES with PCS blocks can be configured to support an array of popular data protocols including PCI Express, Ethernet (1GbE and SGMII), OBSAI and CPRI. Transmit Pre-emphasis and Receive Equalization settings make SERDES suitable for chip to chip and small form factor backplane applications.

Lattice Diamond® design software allows large complex designs to be efficiently implemented using the LatticeECP2/M FPGA family. Synthesis library support for LatticeECP2/M is available for popular logic synthesis tools. The Diamond software uses the synthesis tool output along with the constraints from its floor planning tools to place and route the design in the LatticeECP2/M device. The Diamond design tool extracts the timing from the routing and back-annotates it into the design for timing verification.

Lattice provides many pre-engineered IP (Intellectual Property) modules for the LatticeECP2/M family. By using these IP cores as standardized blocks, designers are free to concentrate on the unique aspects of their design, increasing their productivity.

one clock is selected for each input register, pipeline register and output register. Similarly Clock enable (CE) and Reset (RST) are selected from their four respective sources (CE0, CE1, CE2, CE3 and RST0, RST1, RST2, RST3) at each input register, pipeline register and output register.

Signed and Unsigned with Different Widths

The DSP block supports different widths of signed and unsigned multipliers besides x9, x18 and x36 widths. For unsigned operands, unused upper data bits should be filled to create a valid x9, x18 or x36 operand. For signed two's complement operands, sign extension of the most significant bit should be performed until x9, x18 or x36 width is reached. Table 2-8 provides an example of this.

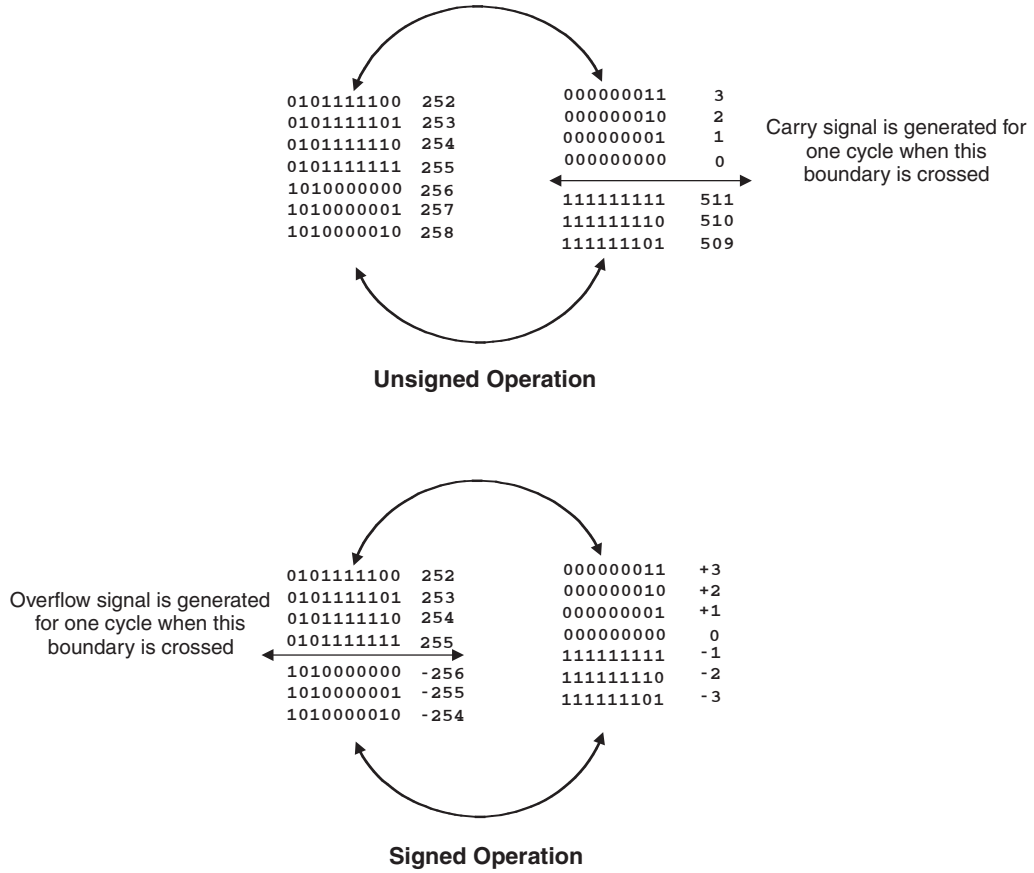
Table 2-8. Sign Extension Example

Number	Unsigned	Unsigned 9-bit	Unsigned 18-bit	Signed	Two's Complement Signed 9 Bits	Two's Complement Signed 18 Bits
+5	0101	000000101	000000000000000101	0101	000000101	000000000000000101
-6	N/A	N/A	N/A	1010	111111010	111111111111111010

OVERFLOW Flag from MAC

The sysDSP block provides an overflow output to indicate that the accumulator has overflowed. When two unsigned numbers are added and the result is a smaller number than the accumulator, "roll-over" is said to have occurred and an overflow signal is indicated. When two positive numbers are added with a negative sum and when two negative numbers are added with a positive sum, then the accumulator "roll-over" is said to have occurred and an overflow signal is indicated. Note that when overflow occurs the overflow flag is present for only one cycle. By counting these overflow pulses in FPGA logic, larger accumulators can be constructed. The conditions overflow signals for signed and unsigned operands are listed in Figure 2-27.

Figure 2-27. Accumulator Overflow/Underflow

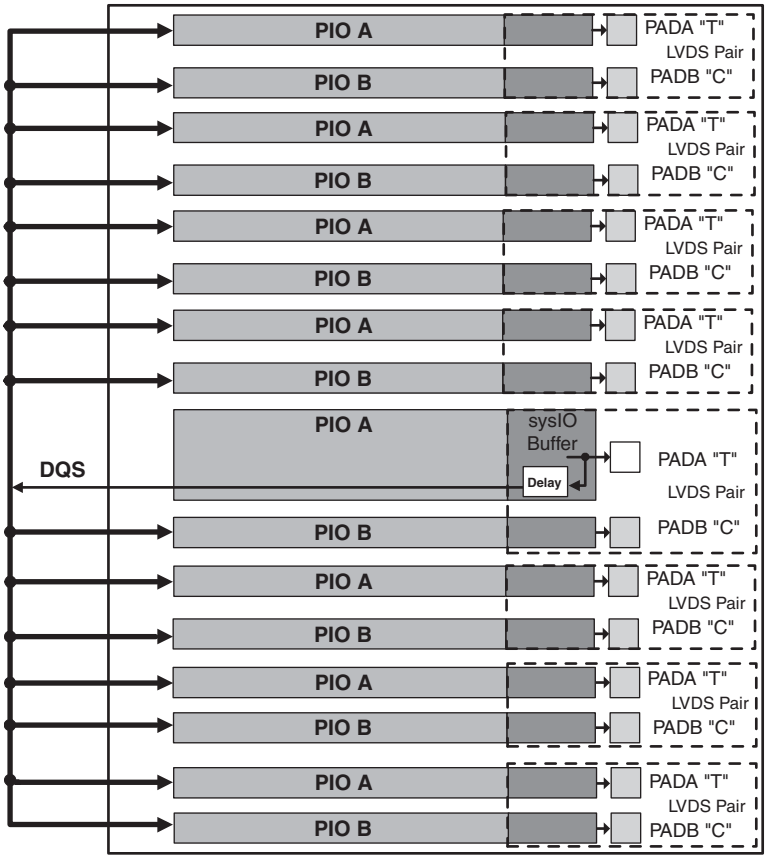


Top Edge

The PICs on the top edge are different from PIOs on the left, right and bottom edges. PIOs on this edge do not have DDR registers or DQS signals.

The exact DQS pins are shown in a dual function in the Logic Signal Connections table in this data sheet. Additional detail is provided in the Signal Descriptions table. The DQS signal from the bus is used to strobe the DDR data from the memory into input register blocks. Interfaces on the left and right edges are designed for DDR memories that support 16 bits of data, whereas interfaces on the bottom are designed for memories that support 18 bits of data.

Figure 2-33. DQS Input Routing for the Left and Right Edges of the Device



IEEE 1149.1-Compliant Boundary Scan Testability

All LatticeECP2/M devices have boundary scan cells that are accessed through an IEEE 1149.1 compliant Test Access Port (TAP). This allows functional testing of the circuit board, on which the device is mounted, through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test data to be captured and shifted out for verification. The test access port consists of dedicated I/Os: TDI, TDO, TCK and TMS. The test access port has its own supply voltage V_{CCJ} and can operate with LVCMOS3.3, 2.5, 1.8, 1.5 and 1.2 standards.

For more details on boundary scan test, please see information regarding additional technical documentation at the end of this data sheet.

Device Configuration

All LatticeECP2/M devices contain two ports that can be used for device configuration. The Test Access Port (TAP), which supports bit-wide configuration, and the sysCONFIG port, support both byte-wide and serial configuration, including the standard SPI Flash interface. The TAP supports both the IEEE Standard 1149.1 Boundary Scan specification and the IEEE Standard 1532 In- System Configuration specification. The sysCONFIG port is a 20-pin interface with six I/Os used as dedicated pins with the remainder used as dual-use pins. See TN1108, LatticeECP2/M sysCONFIG Usage Guide for more information about using the dual-use pins as general purpose I/Os.

On power-up, the FPGA SRAM is ready to be configured using the selected sysCONFIG port. Once a configuration port is selected, it will remain active throughout that configuration cycle. The IEEE 1149.1 port can be activated any time after power-up by sending the appropriate command through the TAP port.

Enhanced Configuration Option

LatticeECP2/M devices have enhanced configuration features such as: decryption support, TransFR™ I/O and dual boot image support.

1. **Decryption Support**
   LatticeECP2/M devices provide on-chip, One Time Programmable (OTP) non-volatile key storage to support decryption of a 128-bit AES encrypted bitstream, securing designs and deterring design piracy.

2. **TransFR (Transparent Field Reconfiguration)**
   TransFR I/O (TFR) is a unique Lattice technology that allows users to update their logic in the field without interrupting system operation using a single ispVM® command. TransFR I/O allows I/O states to be frozen during device configuration. This allows the device to be field updated with a minimum of system disruption and downtime. See TN1087, Minimizing System Interruption During Configuration Using TransFR Technology, for details.

3. **Dual Boot Image Support**
   Dual boot images are supported for applications requiring reliable remote updates of configuration data for the system FPGA. After the system is running with a basic configuration, a new boot image can be downloaded remotely and stored in a separate location in the configuration storage device. Any time after the update the LatticeECP2/M can be re-booted from this new configuration file. If there is a problem, such as corrupt data during download or incorrect version number with this new boot image, the LatticeECP2/M device can revert back to the original backup configuration and try again. This all can be done without power cycling the system.

For more information about device configuration, please see the list of additional technical documentation at the end of this data sheet.

Soft Error Detect (SED) Support

LatticeECP2/M devices have dedicated logic to perform CRC checks. During configuration, the configuration data bitstream can be checked with the CRC logic block. In addition, the LatticeECP2 device can also be programmed

DC Electrical Characteristics

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
I_{IL}, I_{IH}[1, 2]	Input or I/O Low Leakage	$0 \le V_{IN} \le (V_{CCIO} - 0.2V)$	—	—	10	µA
I_{IH}[1, 3]	Input or I/O High Leakage	$(V_{CCIO} - 0.2V) < V_{IN} \le 3.6V$	—	—	150	µA
I_{PU}	I/O Active Pull-up Current	$0 \le V_{IN} \le 0.7\ V_{CCIO}$	-30	—	-210	µA
I_{PD}	I/O Active Pull-down Current	V_{IL} (MAX) $\le V_{IN} \le V_{IH}$ (MAX)	30	—	210	µA
I_{BHLS}	Bus Hold Low Sustaining Current	$V_{IN} = V_{IL}$ (MAX)	30	—	—	µA
I_{BHHS}	Bus Hold High Sustaining Current	$V_{IN} = 0.7\ V_{CCIO}$	-30	—	—	µA
I_{BHLO}	Bus Hold Low Overdrive Current	$0 \le V_{IN} \le V_{CCIO}$	—	—	210	µA
I_{BHHO}	Bus Hold High Overdrive Current	$0 \le V_{IN} \le V_{CCIO}$	—	—	-210	µA
V_{BHT}	Bus Hold Trip Points	$0 \le V_{IN} \le V_{IH}$ (MAX)	V_{IL} (MAX)	—	V_{IH} (MIN)	V
C1[4]	I/O Capacitance	V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V, V_{CC} = 1.2V, V_{IO} = 0 to V_{IH} (MAX)	—	5	8	pf
C2[4]	Dedicated Input Capacitance	V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V, V_{CC} = 1.2V, V_{IO} = 0 to V_{IH} (MAX)	—	5	6	pf

1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tri-stated. It is not measured with the output driver active. Bus maintenance circuits are disabled.
2. When used as V_{REF}, maximum leakage = 25uA
3. Applicable to general purpose I/Os in top and bottom banks.
4. T_A 25°C, f = 1.0MHz.

SERDES Power Supply Requirements (LatticeECP2M Family Only)[1]

Over Recommended Operating Conditions

Symbol	Description	Typ.[2]	Units
Standby (Power Down)			
$I_{CCTX-SB}$	V_{CCTX} current (per channel)	10	µA
$I_{CCRX-SB}$	V_{CCRX} current (per channel)	75	µA
$I_{CCIB-SB}$	Input buffer current (per channel)	0	µA
$I_{CCOB-SB}$	Output buffer current (per channel)	0	µA
I_{CCP-SB}	SERDES PLL current (per quad)	30	µA
$I_{CCAX33-SB}$	SERDES termination current (per quad)	10	µA
Operating (Data Rate = 3.125 Gbps)			
$I_{CCTX-OP}$	V_{CCTX} current (per channel)	19	mA
$I_{CCRX-OP}$	V_{CCRX} current (per channel)	34	mA
$I_{CCIB-OP}$	Input buffer current (per channel)	4	mA
$I_{CCOB-OP}$	Output buffer current (per channel)	13	mA
I_{CCP-OP}	SERDES PLL current (per quad)	26	mA
$I_{CCAX33-OP}$	SERDES termination current (per quad)	0.01	mA

1. Equalization enabled, pre-emphasis disabled.
2. T_J = 25°C, power supplies at nominal voltage.

SERDES Power (LatticeECP2M Family Only)

Table 3-1 presents the SERDES power for one channel.

Table 3-1. SERDES Power[1]

Symbol	Description	Typ.[2]	Units
$P_{S-1CH-31}$	SERDES power (one channel @ 3.125 Gbps)	90	mW
$P_{S-1CH-25}$	SERDES power (one channel @ 2.5 Gbps)	87	mW
$P_{S-1CH-12}$	SERDES power (one channel @ 1.25 Gbps)	86	mW
$P_{S-1CH-02}$	SERDES power (one channel @ 250 Mbps)	76	mW

1. One quarter of the total quad power (includes contribution from common circuits, all channels in the quad operating, pre-emphasis disabled, equalization enabled).
2. Typical values measured at 25ºC and 1.2V.

PCI Express Electrical and Timing Characteristics

AC and DC Characteristics

Table 3-16. Transmit[1, 2]

Symbol	Description	Test Conditions	Min	Typ	Max	Units
UI	Unit interval		399.88	400	400.12	ps
$V_{TX-DIFF\_P-P}$	Differential peak-to-peak output voltage		0.8	1.0	1.2	V
$V_{TX-DE-RATIO}$	De-emphasis differential output voltage ratio		0	-3.5	-7.96	dB
$V_{TX-CM-AC\_P}$	RMS AC peak common-mode output voltage		—	20	—	mV
$V_{TX-CM-DC-LINE-DELTA}$	Maximum Common mode voltage delta between n and p channels		—	—	25	mV
$V_{TX-DC-CM}$	Tx DC common mode voltage		0	—	V_{CCOB} + 5%	V
$I_{TX-SHORT}$	Output short circuit current	V_{TX-D+}=0.0V V_{TX-D-}=0.0V	—	—	90	mA
$Z_{TX-DIFF-DC}$	Differential output impedance		80	100	120	Ohms
$T_{TX-RISE}$	Tx output rise time	20 to 80%	0.125	—	—	UI
$T_{TX-FALL}$	Tx output fall time	20 to 80%	0.125	—	—	UI
$L_{TX-SKEW}$	Lane-to-lane static output skew for all lanes in port/link		—	—	1.3	ns
T_{TX-EYE}	Transmitter eye width		0.75	—	—	UI
$T_{TX-EYE-MEDIAN-TO-MAX-JITTER}$[3]			—	—	0.125	UI
C_{TX}	AC coupling capacitor		75	—	200	nF

1. Values are measured at 2.5 Gbps.
2. Compliant to PCI Express v1.1.
3. Measured at 60ps with plug-in board and jitter due to socket removed.

Table 3-17. Receive

Symbol	Description	Test Conditions	Min.	Typ.	Max.	Units
UI	Unit Interval		399.88	400	400.12	ps
$V_{RX-DIFF\_P-P}$	Differential peak-to-peak input voltage		0.175	—	—	V
$V_{RX-IDLE-DET-DIFF\_P-P}$	Idle detect threshold voltage		65	—	175	mV
$Z_{RX-DIFF-DC}$	DC differential input impedance		80	100	120	Ohms
Z_{RX-DC}	DC input impedance		40	50	60	Ohms
$Z_{RX-HIGH-IMP-DC}$[1]	Power-down DC input impedance		200K	—	—	Ohms
T_{RX-EYE}	Receiver eye width		0.4	—	—	UI
$T_{RX-EYE-MEDIAN-TO-MAX-JITTER}$			—	—	0.3	UI

Notes:
1. Measured with external AC-coupling on the receiver
2. Values are measured at 2.5 Gbps

Table 3-18. Reference Clock

Symbol	Description	Test Conditions	Min.	Typ.	Max.	Units
F_{REFCLK}	Reference clock frequency		—	100	—	MHz
V_{CM}	Input common mode voltage		—	0.65	—	V
T_R/T_F	Clock input rise/fall time		—	—	1.0	ns
V_{SW}	Differential input voltage swing		0.6	—	1.6	V
DC_{REFCLK}	Input clock duty cycle		40	50	60	%
PPM	Reference clock tolerance		-300	—	+300	ppm

LatticeECP2M Power Supply and NC (Cont.)

Signal	672 fpBGA	900 fpBGA
GND[1]	A13, A19, A2, A25, AA2, AA25, AB18, AB22, AB5, AB9, AE1, AE11, AE16, AE22, AE26, AE6, AF13, AF19, AF2, AF25, B1, B11, B16, B22, B26, B6, E18, E22, E5, E9, F2, F25, G11, G16, J22, J5, K11, K13, K14, K16, L10, L11, L16, L17, L2, L20, L25, L7, M13, M14, N10, N12, N13, N14, N15, N17, P10, P12, P13, P14, P15, P17, R13, R14, T10, T11, T16, T17, T2, T20, T25, T7, U11, U13, U14, U16, V22, V5, Y11, Y16	**LFE2M50:** A1, A13, A18, A24, A30, A7, AA14, AA15, AA16, AA17, AA24, AA27, AA4, AB24, AB7, AD12, AD19, AD27, AE22, AE27, AE4, AE9, AF14, AF17, AF25, AF6, AJ10, AJ21, AJ27, AJ4, AK1, AK13, AK18, AK24, AK30, AK7, B10, B21, B27, B4, D25, D6, E14, E17, F22, F27, F4, F9, G12, G19, J24, J7, K14, K15, K16, K17, K27, K4, L14, L15, L16, L17, M23, M8, N14, N15, N16, N17, N27, N4, P11, P13, P14, P15, P16, P17, P18, P20, R10, R11, R13, R14, R15, R16, R17, R18, R20, R21, R24, R7, T10, T11, T13, T14, T15, T16, T17, T18, T20, T21, T24, T7, U11, U13, U14, U15, U16, U17, U18, U20, V14, V15, V16, V17, V27, V4, W23, W8, Y14, Y15, Y16, Y17 **LFE2M70/LFE2M100:** A1, A13, A18, A24, A30, A7, AA14, AA15, AA16, AA17, AA24, AA27, AA4, AB24, AB7, AD12, AD19, AD27, AE22, AE27, AE4, AE9, AF14, AF17, AF25, AF6, AJ10, AJ21, AJ27, AJ4, AK1, AK13, AK18, AK24, AK30, AK7, B10, B21, B27, B4, D25, D6, E14, E17, F22, F27, F4, F9, G12, G19, J24, J7, K14, K15, K16, K17, K27, K4, L14, L15, L16, L17, M23, M8, N14, N15, N16, N17, N27, N4, P11, P13, P14, P15, P16, P17, P18, P20, R10, R11, R13, R14, R15, R16, R17, R18, R20, R21, R24, R7, T10, T11, T13, T14, T15, T16, T17, T18, T20, T21, T24, T7, U11, U13, U14, U15, U16, U17, U18, U20, V14, V15, V16, V17, V27, V4, W23, W8, Y14, Y15, Y16, Y17
NC[2]	**LFE2M35:** AB3, AB4, AC1, AC2, AD15, AD18, AD20, AD23, AE13, AE25, AF16, AF22, B4, B5, C26, D20, D21, D22, D23, D24, D25, D26, E20, E21, E25, E26, F20, G20, K10, K17, R4, U10, U23, V10, W7, N7, V7 **LFE2M50:** AB3, AB4, AC1, AC2, B4, B5, C26, D20, D21, D22, D23, D24, D25, D26, E20, E21, E25, E26, F20, G20, K10, K17, R4, U10, U23, V10, W7, AB21, AC20, AC21, AC22, AC23, AC25, AD26, W20	**LFE2M50:** G5, G4, K7, K8, E1, F2, F1, G3, G2, G1, L9, L7, K6, K5, L8, L6, AA1, AA2, Y3, AB1, Y9, Y8, Y7, AA7, AB2, AB3, AA5, AA6, AB4, AB5, AA8, AA9, AJ1, AK4, AH6, AH3, AH11, AH8, AK10, AJ13, AB26, AB27, Y24, Y25, AA29, Y28, Y30, Y29, W22, V22, Y27, Y26, W30, W29, W25, W26, L24, L23, D30, D29, K24, K25, J27, K26, J26, H26, H27, G26, H23, H24, D28, E28, J18, J19, H17, J17, F18, F17, B13, A10, C8, C11, C3, C6, A4, B1, AA26, AB11, AB12, AB13, AB14, AB15, AB16, AB17, AB19, AB20, AB21, AC11, AC21, AC22, AD21, AD22, AE23, AF20, AF23, AG23, AG26, F20, F23, G10, G20, G21, H19, H20, H21, H22, J20, J21, R9, U22, W9 **LFE2M70/LFE2M100:** AA26, AB10, AB11, AB12, AB13, AB14, AB15, AB16, AB17, AB19, AB20, AB21, AB9, AC10, AC11, AC21, AC22, AC8, AC9, AD21, AD22, AD4, AD5, AD6, AD7, AD8, AE23, AE5, AE6, AE7, AF20, AF23, AF5, AG23, AG26, D10, E10, E11, F10, F20, F23, F8, G10, G20, G21, G7, G8, G9, H19, H20, H21, H22, H6, H8, H9, J10, J20, J21, J9, K9, R9, U22, W9

1. All grounds must be electrically connected at the board level. For fpBGA packages, the total number of GND balls is less than the actual number of GND logic connections from the die to the common package GND plane.
2. NC pins should not be connected to any active signals, VCC or GND.
3. For package migration across device densities, the designer must comprehend the package pin requirements for the SERDES blocks. Specifically, the SERDES power pins of the largest density device must be accounted to accommodate migration to other smaller devices using the same package. Please refer to TN1160, LatticeECP2/M Density Migration for more details.

LFE2-12E/SE and LFE2-20E/SE Logic Signal Connections: 208 PQFP

LFE2-12E/SE					LFE2-20E/SE			
Pin Number	Pin/Pad Function	Bank	Dual Function	Differential	Pin/Pad Function	Bank	Dual Function	Differential
1	PL2A	7	VREF2_7	T (LVDS)*	PL2A	7	VREF2_7	T (LVDS)*
2	PL2B	7	VREF1_7	C (LVDS)*	PL2B	7	VREF1_7	C (LVDS)*
3	PL4A	7		T (LVDS)*	PL6A	7	LDQ8	T (LVDS)*
4	PL4B	7		C (LVDS)*	PL6B	7	LDQ8	C (LVDS)*
5	GND	-			GND	-		
6	PL6A	7	LDQ10	T (LVDS)*	PL12A	7	LDQ16	T (LVDS)*
7	VCCAUX	-			VCCAUX	-		
8	PL6B	7	LDQ10	C (LVDS)*	PL12B	7	LDQ16	C (LVDS)*
9	PL8A	7	LDQ10	T (LVDS)*	PL14A	7	LDQ16	T (LVDS)*
10	VCCIO7	7			VCCIO7	7		
11	PL8B	7	LDQ10	C (LVDS)*	PL14B	7	LDQ16	C (LVDS)*
12	VCC	-			VCC	-		
13	GND	-			GND	-		
14	VCCIO7	7			VCCIO7	7		
15	PL12A	7	LDQ10	T (LVDS)*	PL18A	7	LDQ16	T (LVDS)*
16	PL12B	7	LDQ10	C (LVDS)*	PL18B	7	LDQ16	C (LVDS)*
17	GND	-			GND	-		
18	PL13A	7	PCLKT7_0/LDQ10	T	PL19A	7	PCLKT7_0/LDQ16	T
19	VCC	-			VCC	-		
20	PL13B	7	PCLKC7_0/LDQ10	C	PL19B	7	PCLKC7_0/LDQ16	C
21	PL15A	6	PCLKT6_0	T (LVDS)*	PL21A	6	PCLKT6_0/LDQ25	T (LVDS)*
22	PL15B	6	PCLKC6_0	C (LVDS)*	PL21B	6	PCLKC6_0/LDQ25	C (LVDS)*
23	PL16A	6	VREF2_6	T	PL22A	6	VREF2_6/LDQ25	T
24	PL16B	6	VREF1_6	C	PL22B	6	VREF1_6/LDQ25	C
25	GND	-			GND	-		
26	PL17A	6	LLM0_GDLLT_IN_A**	T (LVDS)*	PL27A	6	LLM0_GDLLT_IN_A**/LDQ25	T (LVDS)*
27	PL17B	6	LLM0_GDLLC_IN_A**	C (LVDS)*	PL27B	6	LLM0_GDLLC_IN_A**/LDQ25	C (LVDS)*
28	VCC	-			VCC	-		
29	LLM0_PLLCAP	6			LLM0_PLLCAP	6		
30	VCCAUX	-			VCCAUX	-		
31	PL20A	6	LLM0_GPLLT_IN_A**	T (LVDS)*	PL30A	6	LLM0_GPLLT_IN_A**/LDQ34	T (LVDS)*
32	GND	-			GND	-		
33	PL21A	6	LLM0_GPLLT_FB_A	T	PL31A	6	LLM0_GPLLT_FB_A/LDQ34	T
34	PL20B	6	LLM0_GPLLC_IN_A**	C (LVDS)*	PL30B	6	LLM0_GPLLC_IN_A**/LDQ34	C (LVDS)*
35	PL21B	6	LLM0_GPLLC_FB_A	C	PL31B	6	LLM0_GPLLC_FB_A/LDQ34	C
36	PL23A	6			PL33A	6	LDQ34	
37	PL24A	6	LDQ28	T (LVDS)*	PL38A	6	LDQ42	T (LVDS)*
38	VCCIO6	6			VCCIO6	6		
39	PL24B	6	LDQ28	C (LVDS)*	PL38B	6	LDQ42	C (LVDS)*
40	VCC	-			VCC	-		
41	PL26A	6	LDQ28	T (LVDS)*	PL40A	6	LDQ42	T (LVDS)*
42	GND	-			GND	-		
43	PL26B	6	LDQ28	C (LVDS)*	PL40B	6	LDQ42	C (LVDS)*
44	VCCIO6	6			VCCIO6	6		
45	PL28A	6	LDQS28	T (LVDS)*	PL42A	6	LDQS42	T (LVDS)*

LFE2-50E/SE and LFE2-70E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-50E/SE					LFE2-70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
AE17	PB60B	4	BDQ60	C	PB69B	4	BDQ69	C
AB19	PB61A	4	BDQ60	T	PB70A	4	BDQ69	T
AE19	PB61B	4	BDQ60	C	PB70B	4	BDQ69	C
AF17	PB62A	4	BDQ60	T	PB71A	4	BDQ69	T
AE18	PB62B	4	BDQ60	C	PB71B	4	BDQ69	C
VCCIO	VCCIO4	4			VCCIO4	4		
W16	PB63A	4	BDQ60	T	PB72A	4	BDQ69	T
AA17	PB63B	4	BDQ60	C	PB72B	4	BDQ69	C
AF18	PB64A	4	BDQ60	T	PB73A	4	BDQ69	T
AF19	PB64B	4	BDQ60	C	PB73B	4	BDQ69	C
GND	GNDIO4	-			GNDIO4	-		
AA19	PB65A	4	BDQ69	T	PB74A	4	BDQ78	T
W17	PB65B	4	BDQ69	C	PB74B	4	BDQ78	C
Y19	PB66A	4	BDQ69	T	PB75A	4	BDQ78	T
Y17	PB66B	4	BDQ69	C	PB75B	4	BDQ78	C
AF20	PB67A	4	BDQ69	T	PB76A	4	BDQ78	T
VCCIO	VCCIO4	4			VCCIO4	4		
AE20	PB67B	4	BDQ69	C	PB76B	4	BDQ78	C
AA20	PB68A	4	BDQ69	T	PB77A	4	BDQ78	T
W18	PB68B	4	BDQ69	C	PB77B	4	BDQ78	C
AD20	PB69A	4	BDQS69	T	PB78A	4	BDQS78	T
GND	GNDIO4	-			GNDIO4	-		
AE21	PB69B	4	BDQ69	C	PB78B	4	BDQ78	C
AF21	PB70A	4	BDQ69	T	PB79A	4	BDQ78	T
AF22	PB70B	4	BDQ69	C	PB79B	4	BDQ78	C
VCCIO	VCCIO4	4			VCCIO4	4		
GND	GNDIO4	-			GNDIO4	-		
AE22	PB74A	4	BDQ78	T	PB92A	4	BDQ96	T
AD22	PB74B	4	BDQ78	C	PB92B	4	BDQ96	C
AF23	PB75A	4	BDQ78	T	PB93A	4	BDQ96	T
AE23	PB75B	4	BDQ78	C	PB93B	4	BDQ96	C
AD23	PB76A	4	BDQ78	T	PB94A	4	BDQ96	T
AC23	PB76B	4	BDQ78	C	PB94B	4	BDQ96	C
VCCIO	VCCIO4	4			VCCIO4	4		
AB20	PB77A	4	BDQ78	T	PB95A	4	BDQ96	T
AC20	PB77B	4	BDQ78	C	PB95B	4	BDQ96	C
GND	GNDIO4	-			GNDIO4	-		
AB21	PB78A	4	BDQS78	T	PB96A	4	BDQS96	T
AC22	PB78B	4	BDQ78	C	PB96B	4	BDQ96	C
W19	PB79A	4	BDQ78	T	PB97A	4	BDQ96	T
AA21	PB79B	4	BDQ78	C	PB97B	4	BDQ96	C
AF24	PB80A	4	BDQ78	T	PB98A	4	BDQ96	T
AE24	PB80B	4	BDQ78	C	PB98B	4	BDQ96	C
VCCIO	VCCIO4	4			VCCIO4	4		
Y20	PB81A	4	BDQ78	T	PB99A	4	BDQ96	T
AB22	PB81B	4	BDQ78	C	PB99B	4	BDQ96	C

LFE2-70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2-70E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
E21	PT76A	1		T
VCCIO	VCCIO1	1		
B22	PT75B	1		C
A22	PT75A	1		T
H20	PT74B	1		C
F21	PT74A	1		T
F20	PT73B	1		C
GND	GNDIO1	-		
H19	PT73A	1		T
D21	PT72B	1		C
C21	PT72A	1		T
E20	PT71B	1		C
VCCIO	VCCIO1	1		
G21	PT71A	1		T
B21	PT70B	1		C
A21	PT70A	1		T
F19	PT69B	1		C
G20	PT69A	1		T
E19	PT68B	1		C
GND	GNDIO1	-		
G19	PT68A	1		T
D20	PT67B	1		C
VCCIO	VCCIO1	1		
C20	PT67A	1		T
B20	PT66B	1		C
A20	PT66A	1		T
F18	PT65B	1		C
H18	PT65A	1		T
D19	PT64B	1		C
C19	PT64A	1		T
GND	GNDIO1	-		
G18	PT63B	1		C
E18	PT63A	1		T
H17	PT62B	1		C
F17	PT62A	1		T
VCCIO	VCCIO1	1		
G17	PT61B	1		C
E17	PT61A	1		T
B19	PT60B	1		C
A19	PT60A	1		T
GND	GNDIO1	-		
D17	PT59B	1		C
B18	PT59A	1		T

LFE2M20E/SE and LFE2M35E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2M20E/SE					LFE2M35E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
G18	VCCIO2	2			VCCIO2	2		
J15	VCCIO2	2			VCCIO2	2		
K19	VCCIO2	2			VCCIO2	2		
N19	VCCIO3	3			VCCIO3	3		
P15	VCCIO3	3			VCCIO3	3		
T18	VCCIO3	3			VCCIO3	3		
V21	VCCIO3	3			VCCIO3	3		
AA18	VCCIO4	4			VCCIO4	4		
R14	VCCIO4	4			VCCIO4	4		
V16	VCCIO4	4			VCCIO4	4		
W13	VCCIO4	4			VCCIO4	4		
AA5	VCCIO5	5			VCCIO5	5		
R9	VCCIO5	5			VCCIO5	5		
V7	VCCIO5	5			VCCIO5	5		
W10	VCCIO5	5			VCCIO5	5		
N4	VCCIO6	6			VCCIO6	6		
P8	VCCIO6	6			VCCIO6	6		
T5	VCCIO6	6			VCCIO6	6		
V2	VCCIO6	6			VCCIO6	6		
E2	VCCIO7	7			VCCIO7	7		
G5	VCCIO7	7			VCCIO7	7		
J8	VCCIO7	7			VCCIO7	7		
K4	VCCIO7	7			VCCIO7	7		
AA22	VCCIO8	8			VCCIO8	8		
U19	VCCIO8	8			VCCIO8	8		
H11	VCCAUX	-			VCCAUX	-		
H12	VCCAUX	-			VCCAUX	-		
L15	VCCAUX	-			VCCAUX	-		
L8	VCCAUX	-			VCCAUX	-		
M15	VCCAUX	-			VCCAUX	-		
M8	VCCAUX	-			VCCAUX	-		
R11	VCCAUX	-			VCCAUX	-		
R12	VCCAUX	-			VCCAUX	-		
A1	GND	-			GND	-		
A10	GND	-			GND	-		
A16	GND	-			GND	-		
A22	GND	-			GND	-		
AA19	GND	-			GND	-		
AA4	GND	-			GND	-		
AB1	GND	-			GND	-		
AB22	GND	-			GND	-		
B13	GND	-			GND	-		
B19	GND	-			GND	-		
B4	GND	-			GND	-		
D16	GND	-			GND	-		
D2	GND	-			GND	-		
D21	GND	-			GND	-		
D7	GND	-			GND	-		

LFE2M50E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2M50E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
T1	PL65A	6	LLM0_GDLLT_FB_A	T
T2	PL65B	6	LLM0_GDLLC_FB_A	C
GNDIO	GNDIO6	-		
R7	LLM0_PLLCAP	6		
T6	PL67A	6	LDQ71	T (LVDS)*
T7	PL67B	6	LDQ71	C (LVDS)*
U1	PL68A	6	LDQ71	T
U2	PL68B	6	LDQ71	C
VCCIO	VCCIO6	6		
T3	PL69A	6	LDQ71	T (LVDS)*
U3	PL69B	6	LDQ71	C (LVDS)*
U6	PL70A	6	LDQ71	T
U5	PL70B	6	LDQ71	C
GNDIO	GNDIO6	-		
V5	PL71A	6	LDQS71	T (LVDS)*
U4	PL71B	6	LDQ71	C (LVDS)*
V1	PL72A	6	LDQ71	T
VCCIO	VCCIO6	6		
V3	PL72B	6	LDQ71	C
W1	PL73A	6	LDQ71	T (LVDS)*
Y1	PL73B	6	LDQ71	C (LVDS)*
AA1	PL74A	6	LDQ71	T
GNDIO	GNDIO6	-		
AA2	PL74B	6	LDQ71	C
V4	TCK	-		
Y2	TDI	-		
Y3	TMS	-		
W3	TDO	-		
W4	VCCJ	-		
W5	PB2A	5	BDQ6	T
Y4	PB2B	5	BDQ6	C
W6	PB3A	5	BDQ6	T
V6	PB3B	5	BDQ6	C
AA3	PB4A	5	BDQ6	T
AB2	PB4B	5	BDQ6	C
VCCIO	VCCIO5	5		
T8	PB5A	5	BDQ6	T
U7	PB5B	5	BDQ6	C
GNDIO	GNDIO5	-		
U8	PB6A	5	BDQS6	T
T9	PB6B	5	BDQ6	C
V8	PB7A	5	BDQ6	T
W8	PB7B	5	BDQ6	C

LFE2M50E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2M50E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
U12	PB59B	4	BDQ60	C
GNDIO	GNDIO4	-		
AA12	PB60A	4	BDQS60	T
Y12	PB60B	4	BDQ60	C
V12	PB61A	4	BDQ60	T
W12	PB61B	4	BDQ60	C
AB12	PB62A	4	BDQ60	T
AA13	PB62B	4	BDQ60	C
VCCIO	VCCIO4	4		
T12	PB63A	4	BDQ60	T
U13	PB63B	4	BDQ60	C
V13	PB64A	4	BDQ60	T
T13	PB64B	4	BDQ60	C
GNDIO	GNDIO4	-		
AB13	PB65A	4	BDQ69	T
AB14	PB65B	4	BDQ69	C
U14	PB66A	4	BDQ69	T
T14	PB66B	4	BDQ69	C
AA14	PB67A	4	BDQ69	T
VCCIO	VCCIO4	4		
Y14	PB67B	4	BDQ69	C
W14	PB68A	4	BDQ69	T
V14	PB68B	4	BDQ69	C
AB15	PB69A	4	BDQS69	T
GNDIO	GNDIO4	-		
AA15	PB69B	4	BDQ69	C
V15	PB70A	4	BDQ69	T
U15	PB70B	4	BDQ69	C
AB16	PB71A	4	BDQ69	T
VCCIO	VCCIO4	4		
AA16	PB71B	4	BDQ69	C
AB17	PB72A	4	BDQ69	T
AA17	PB72B	4	BDQ69	C
GNDIO	GNDIO4	-		
W20	CFG2	8		
V20	CFG1	8		
V19	CFG0	8		
V22	PROGRAMN	8		
W22	CCLK	8		
U18	INITN	8		
U22	DONE	8		
GNDIO	GNDIO8	-		
U20	WRITEN***	8		

LFE2M50E/SE and LFE2M70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M50E/SE					LFE2M70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
P13	GND	-			GND	-		
P14	GND	-			GND	-		
P15	GND	-			GND	-		
P16	GND	-			GND	-		
P17	GND	-			GND	-		
P18	GND	-			GND	-		
P20	GND	-			GND	-		
R10	GND	-			GND	-		
R11	GND	-			GND	-		
R13	GND	-			GND	-		
R14	GND	-			GND	-		
R15	GND	-			GND	-		
R16	GND	-			GND	-		
R17	GND	-			GND	-		
R18	GND	-			GND	-		
R20	GND	-			GND	-		
R21	GND	-			GND	-		
R24	GND	-			GND	-		
R7	GND	-			GND	-		
T10	GND	-			GND	-		
T11	GND	-			GND	-		
T13	GND	-			GND	-		
T14	GND	-			GND	-		
T15	GND	-			GND	-		
T16	GND	-			GND	-		
T17	GND	-			GND	-		
T18	GND	-			GND	-		
T20	GND	-			GND	-		
T21	GND	-			GND	-		
T24	GND	-			GND	-		
T7	GND	-			GND	-		
U11	GND	-			GND	-		
U13	GND	-			GND	-		
U14	GND	-			GND	-		
U15	GND	-			GND	-		
U16	GND	-			GND	-		
U17	GND	-			GND	-		
U18	GND	-			GND	-		
U20	GND	-			GND	-		
V14	GND	-			GND	-		
V15	GND	-			GND	-		
V16	GND	-			GND	-		
V17	GND	-			GND	-		
V27	GND	-			GND	-		
V4	GND	-			GND	-		
W23	GND	-			GND	-		
W8	GND	-			GND	-		
Y14	GND	-			GND	-		

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
U7	PL60A	6	VREF2_6/LDQ63	T
T8	PL60B	6	VREF1_6/LDQ63	C
R3	PL61A	6	LDQ63	T (LVDS)*
VCCIO	VCCIO6	6		
R2	PL61B	6	LDQ63	C (LVDS)*
R1	PL62A	6	LDQ63	T
T1	PL62B	6	LDQ63	C
GNDIO	GNDIO6	-		
VCCIO	VCCIO6	6		
T3	PL65A	6	LLM4_SPLLT_IN_A/LDQ63	T (LVDS)*
T2	PL65B	6	LLM4_SPLLC_IN_A/LDQ63	C (LVDS)*
U9	PL66A	6	LLM4_SPLLT_FB_A/LDQ63	T
U8	PL66B	6	LLM4_SPLLC_FB_A/LDQ63	C
GNDIO	GNDIO6	-		
U5	PL68A	6	LDQ72	T (LVDS)*
U4	PL68B	6	LDQ72	C (LVDS)*
V9	PL69A	6	LDQ72	T
V7	PL69B	6	LDQ72	C
VCCIO	VCCIO6	6		
U3	PL70A	6	LDQ72	T (LVDS)*
U2	PL70B	6	LDQ72	C (LVDS)*
V8	PL71A	6	LDQ72	T
U6	PL71B	6	LDQ72	C
GNDIO	GNDIO6	-		
U1	PL72A	6	LDQS72	T (LVDS)*
V2	PL72B	6	LDQ72	C (LVDS)*
V5	PL73A	6	LDQ72	T
VCCIO	VCCIO6	6		
V6	PL73B	6	LDQ72	C
V1	PL74A	6	LDQ72	T (LVDS)*
W1	PL74B	6	LDQ72	C (LVDS)*
W5	PL75A	6	LDQ72	T
GNDIO	GNDIO6	-		
W6	PL75B	6	LDQ72	C
W3	PL77A	6	LDQ81	T (LVDS)*
W4	PL77B	6	LDQ81	C (LVDS)*
W2	PL78A	6	LDQ81	T
Y4	PL78B	6	LDQ81	C
Y1	PL79A	6	LDQ81	T (LVDS)*
VCCIO	VCCIO6	6		
Y2	PL79B	6	LDQ81	C (LVDS)*
Y5	PL80A	6	LDQ81	T
Y6	PL80B	6	LDQ81	C

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
AA1	PL81A	6	LDQS81	T (LVDS)*
GNDIO	GNDIO6	-		
AA2	PL81B	6	LDQ81	C (LVDS)*
Y3	PL82A	6	LDQ81	T
AB1	PL82B	6	LDQ81	C
VCCIO	VCCIO6	6		
Y9	PL83A	6	LDQ81	T (LVDS)*
Y8	PL83B	6	LDQ81	C (LVDS)*
Y7	PL84A	6	LDQ81	T
AA7	PL84B	6	LDQ81	C
GNDIO	GNDIO6	-		
VCCIO	VCCIO6	6		
AB2	PL95A	6	LDQ99	T (LVDS)*
AB3	PL95B	6	LDQ99	C (LVDS)*
AA5	PL96A	6	LDQ99	T
AA6	PL96B	6	LDQ99	C
AB4	PL97A	6	LDQ99	T (LVDS)*
VCCIO	VCCIO6	6		
AB5	PL97B	6	LDQ99	C (LVDS)*
AA8	PL98A	6	LDQ99	T
AA9	PL98B	6	LDQ99	C
AC1	PL99A	6	LLM0_GPLLT_IN_A**/LDQS99	T (LVDS)*
GNDIO	GNDIO6	-		
AC2	PL99B	6	LLM0_GPLLC_IN_A**/LDQ99	C (LVDS)*
AC4	PL100A	6	LLM0_GPLLT_FB_A/LDQ99	T
AC3	PL100B	6	LLM0_GPLLC_FB_A/LDQ99	C
VCCIO	VCCIO6	6		
AC7	PL101A	6	LLM0_GDLLT_IN_A**/LDQ99	T (LVDS)*
AC6	PL101B	6	LLM0_GDLLC_IN_A**/LDQ99	C (LVDS)*
AC5	PL102A	6	LLM0_GDLLT_FB_A/LDQ99	T
AD3	PL102B	6	LLM0_GDLLC_FB_A/LDQ99	C
GNDIO	GNDIO6	-		
AB8	LLM0_PLLCAP	6		
AD2	PL104A	6		T
AD1	PL104B	6		C
AE2	TCK	-		
AE1	TDI	-		
AF2	TMS	-		
AF1	TDO	-		
AG1	VCCJ	-		
AH1	LLC_SQ_VCCRX3	14		
AK2	LLC_SQ_HDINP3	14		T
AJ1	LLC_SQ_VCCIB3	14		

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
AJ2	LLC_SQ_HDINN3	14		C
AH4	LLC_SQ_VCCTX3	14		
AK5	LLC_SQ_HDOUTP3	14		T
AK4	LLC_SQ_VCCOB3	14		
AJ5	LLC_SQ_HDOUTN3	14		C
AH5	LLC_SQ_VCCTX2	14		
AJ6	LLC_SQ_HDOUTN2	14		C
AH6	LLC_SQ_VCCOB2	14		
AK6	LLC_SQ_HDOUTP2	14		T
AH2	LLC_SQ_VCCRX2	14		
AJ3	LLC_SQ_HDINN2	14		C
AH3	LLC_SQ_VCCIB2	14		
AK3	LLC_SQ_HDINP2	14		T
AH7	LLC_SQ_VCCP	14		
AG7	LLC_SQ_REFCLKP	14		T
AF7	LLC_SQ_REFCLKN	14		C
AJ7	LLC_SQ_VCCAUX33	14		
AK11	LLC_SQ_HDINP1	14		T
AH11	LLC_SQ_VCCIB1	14		
AJ11	LLC_SQ_HDINN1	14		C
AH12	LLC_SQ_VCCRX1	14		
AK8	LLC_SQ_HDOUTP1	14		T
AH8	LLC_SQ_VCCOB1	14		
AJ8	LLC_SQ_HDOUTN1	14		C
AH9	LLC_SQ_VCCTX1	14		
AJ9	LLC_SQ_HDOUTN0	14		C
AK10	LLC_SQ_VCCOB0	14		
AK9	LLC_SQ_HDOUTP0	14		T
AH10	LLC_SQ_VCCTX0	14		
AJ12	LLC_SQ_HDINN0	14		C
AJ13	LLC_SQ_VCCIB0	14		
AK12	LLC_SQ_HDINP0	14		T
AH13	LLC_SQ_VCCRX0	14		
AF10	PB30A	5	BDQ33	T
AE8	PB30B	5	BDQ33	C
AE11	PB31A	5	BDQ33	T
VCCIO	VCCIO5	5		
AD9	PB31B	5	BDQ33	C
AE10	PB32A	5	BDQ33	T
AD10	PB32B	5	BDQ33	C
AE13	PB33A	5	BDQS33	T
GNDIO	GNDIO5	-		
AC12	PB33B	5	BDQ33	C

Date	Version	Section	Change Summary
June 2013 (cont.)	04.0 (cont.)	DC and Switching Characteristics	sysCLOCK SPLL Timing table – Corrected signal names for t_{RST} parameter.
			LatticeECP2/M sysCONFIG Port Timing Specifications table – added t_{SUMCDI} and t_{HMCDI} parameters.
September 2013	04.1	Architecture	Updated Selectable Master Clock (CCLK) Frequencies during Configuration table.
		DC and Switching Characteristics	Added information on f_{MAXSPI} parameter in LatticeECP2/M sysCONFIG Port Timing Specifications table.